



N-Channel 30-V (D-S), 175 °C MOSFET

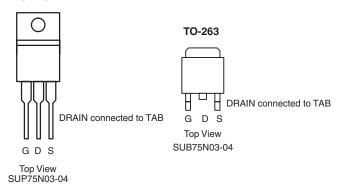
PRODUCT SUMMARY			
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)	
30	0.004	75 ^a	

FEATURES

- TrenchFET® Power MOSFETs
- 175 °C Rated Maximum Junction Temperature



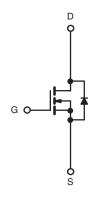
TO-220AB



Ordering Information: SUP75N03-04

SUP75N03-04-E3 (Lead (Pb)-free) SUB75N03-04

SUB75N03-04-E3 (Lead (Pb)-free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	S $T_C = 25$ °C, unless otherwis	e noted			
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current (T _J = 175 °C)	T _C = 25 °C	I _D	75 ^a		
	T _C = 125 °C		75 ^a	i	
Pulsed Drain Current		I _{DM}	250	А	
Pulse Diode Forward Current		I _{SM}	250		
Continuous Source Current (Diode Conduction)		I _S	75		
Avalanche Current		I _{AR}	75		
Avalanche Energy	L = 0.1 mH	E _{AS}	280	ml	
Repetitive Avalanche Energy ^b	L = 0.05 mH	E _{AR}	140	— mJ	
Maximum Power Dissipation	T _C = 25 °C (TO-220AB and TO-263)	P _D	187 ^c	W	
	T _A = 25 °C (TO-263) ^d		3.7		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	
Lead Temperature (1/16" from case for 10 sec.)	TO-220AB	T _L	T _L 300		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) ^d	R _{thJA}	40	°C/W	
	Free Air (TO-220AB)	thJA	62.5		
Junction-to-Case		R _{thJC}	0.6		

Notes:

- a. Package limited.
- b. Duty cycle ≤ 1 %.
- c. See SOA curve for voltage derating.
 d. When Mounted on 1" square PCB (FR-4 material).

For SPICE model information via the Worldwide Web: http://www.vishay.com/www/product/spice.htm.

* Pb containing terminations are not RoHS compliant, exemptions may apply

SUP/SUB75N03-04

Vishay Siliconix



Parameter	Symbol	Test Conditions	Min	Typ ^a	Max	Unit
Static				<u>'</u>	<u> </u>	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	30			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		3	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 500	nA
Zero Gate Voltage Drain Current		V _{DS} = 30 V, V _{GS} = 0 V			1	μΑ
	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			200	
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α
Drain-Source On-State Resistance ^b		V _{GS} = 10 V, I _D = 75 A		0.0034	0.004	Ω
	_	$V_{GS} = 4.5 \text{ V}, I_D = 75 \text{ A}$		0.005	0.006	
	rDS(on)	$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}, T_J = 125 ^{\circ}\text{C}$			0.006	
		$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}, T_J = 175 ^{\circ}\text{C}$			0.008	
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 25 A	30			S
Dynamic						
Input Capacitance	C _{iss}			10742		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		1811		
Reverse Transfer Capacitance	C _{rss}			775		
Total Gate Charge	Qg	V _{DS} = 30 V, V _{GS} = 10 V, I _D = 75 A		200	250	nC
Gate-Source Charge	Q _{gs}			40		
Gate-Drain Charge	Q _{gd}			40		
Turn-On Delay Time	t _{d(on)}	V_{DD} = 30 V, R_L = 0.6 Ω I_D \cong 50 A, V_{GEN} = 10 V, R_G = 2.5 Ω		20	40	ns
Rise Time	t _r			40		
Turn-Off Delay Time	t _{d(off)}			190		
Fall Time	t _f			95		
Source-Drain Diode Ratings and Cha	aracteristics					
Diode Forward Voltage ^b	V_{SD}	$I_F = 75 \text{ A}, V_{GS} = 0 \text{ V}$			1.3	٧
Reverse Recovery Time	t _{rr}			70	120	ns
Peak Reverse Recovery Current	I _{RM(rec)}	I _F = 50 A, di/dt = 100 A/μs		2.8	6	Α
Reverse Recovery Charge	Q _{rr}			0.1	0.36	μC

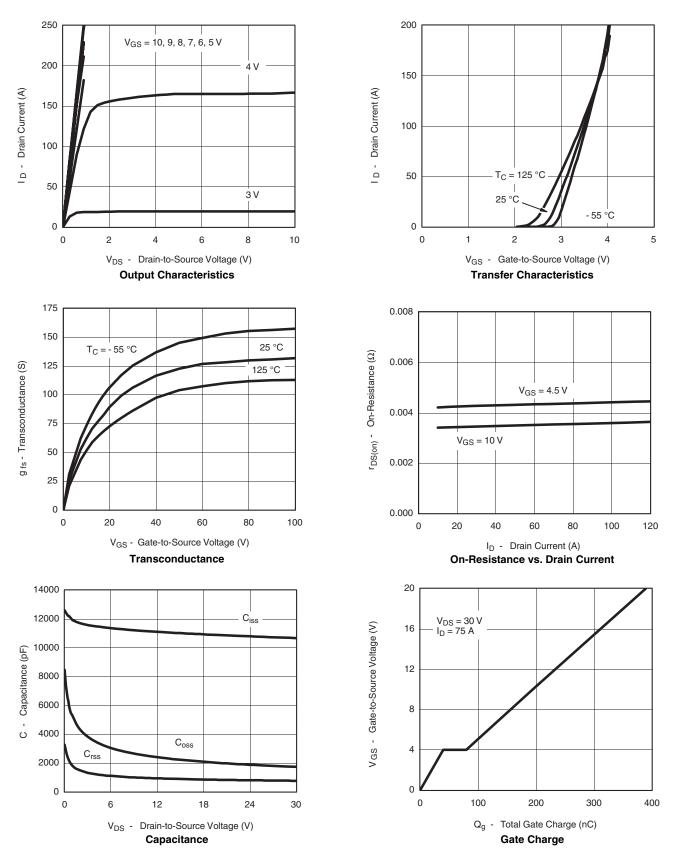
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. For design aid only; not subject to production testing.

b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.



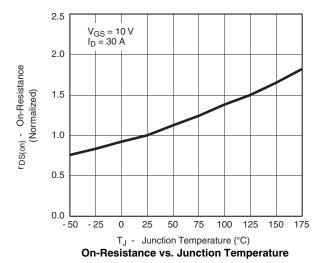
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

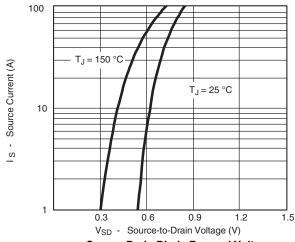


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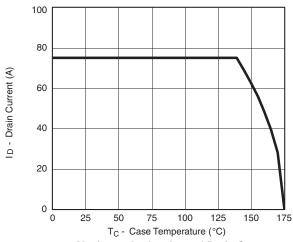
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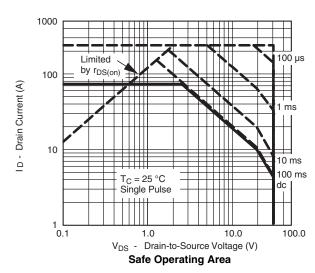




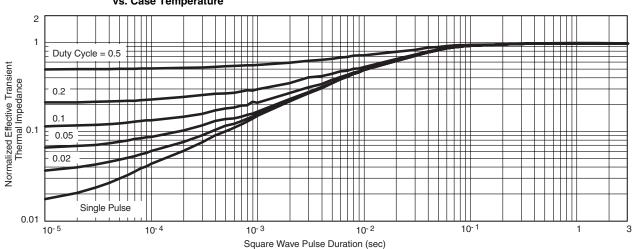
Source-Drain Diode Forward Voltage

THERMAL RATINGS





Maximum Avalanche and Drain Current vs. Case Temperature



Normalized Thermal Transient Impedance, Junction-to-Case

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